

### Problem 1

- KP 1: Correct Identification of Conductive Path (3)
- KP 2: Correct Identification of Insulation (3)
- KP 3: Initial Coating with Copper [How] (5)
- KP 4: Removal of Unwanted Copper [How] (6)
- KP 5: How Conductive Path and Insulation Remain after KP's 3 and 4 (3)

### Problem 2

- KP 1: Ensuring Only Area where we want Boron is Exposed [How] (8)
- KP 2: Putting in Boron [How] (5)
- KP 3: Ensuring Only Area where want Metallization is Exposed [How] (4)
- KP 4: Metallization (3)

### Problem 3

- KP 1: Correct Identification of Component as IC Package (4)
- KP 2: Connection to Populated Circuit Board (4)
- KP 3: Role of Package (4)
- KP 4: Connection of IC to Parts of Package which Connect to Populated Circuit Board (8)